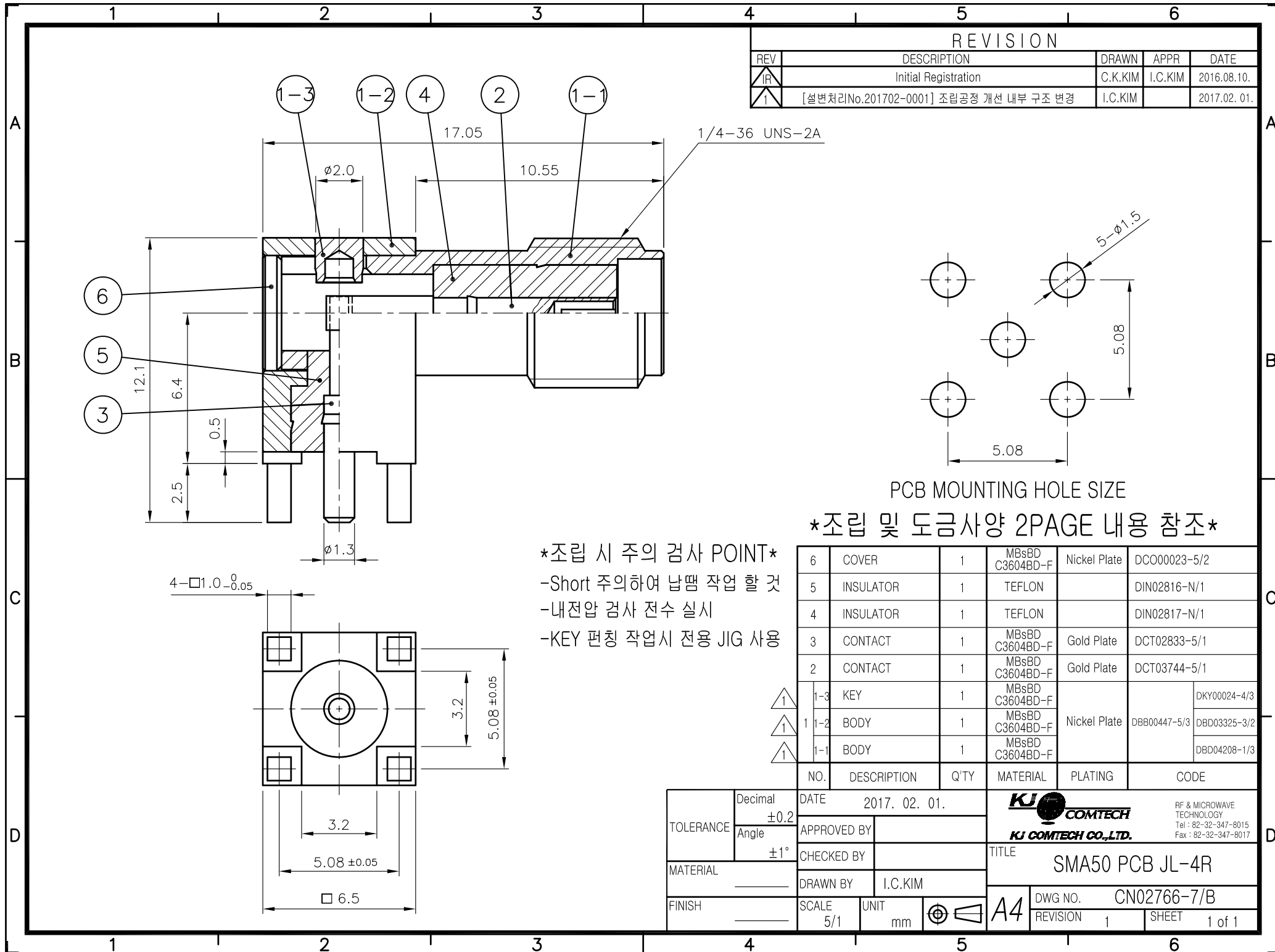




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	C.K.KIM	I.C.KIM	2016.08.10.
1	[설번처리No.201702-0001] 조립공정 개선 내부 구조 변경	I.C.KIM		2017.02. 01.

조립 시 주의 검사 POINT

- Short 주의하여 납땜 작업 할 것
- 내전압 검사 전수 실시
- KEY 펀칭 작업시 전용 JIG 사용

* 것 용	6	COVER	1	MBsBD C3604BD-F	Nickel Plate	DCO00023-5/2	
	5	INSULATOR	1	TEFLON		DIN02816-N/1	
	4	INSULATOR	1	TEFLON		DIN02817-N/1	
	3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT02833-5/1	
	2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03744-5/1	
△ 1	1-3	KEY	1	MBsBD C3604BD-F	Nickel Plate		DKY00024-4/3
△ 1	1-2	BODY	1	MBsBD C3604BD-F		DBB00447-5/3	DBD03325-3/2
△ 1	1-1	BODY	1	MBsBD C3604BD-F			DBD04208-1/3
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE	
mal ±0.2	DATE 2017. 02. 01.			 KJ COMTECH CO.,LTD.		RF & MICROWAVE TECHNOLOGY	
e ±1°	APPROVED BY					Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	CHECKED BY			TITLE			
	DRAWN BY I.C.KIM			SMA50 PCB JL-4R			
	SCALE 5/1	UNIT mm		A4	DWG NO. REVISION 1	CN02766-7/B SHEET 1 of 1	